SPC TECHNOLOGY

ALL RIGHTS RESERVED. NO PORTION OF THIS PUBLICATION, WHETHER IN WHOLE OR IN PART CAN BE REPRODUCED WITHOUT THE EXPRESS WRITTEN CONSENT OF SPC TECHNOLOGY.

SPC-F005.DWG

REVISIONS

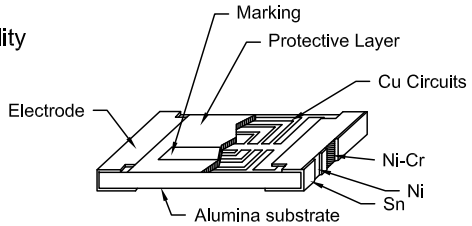
DOC. NO. SPC-F005 * Effective: 7/8/02 * DCP No: 1398

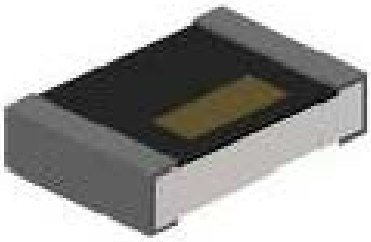
DCP #	REV	DESCRIPTION	DRAWN	DATE	CHECKD	DATE	APPRVD	DATE
2048	A	RELEASED	JN	05/21/09	JWM	05/21/09	JWM	05/21/09

Features

- Photolithographic single layer ceramic chip
- High SRF, excellent Q, superior temperature stability
- Tight tolerance of ± 1% or ± 0.1nH
- Self resonant frequency controlled within 10%
- Stable inductance in high frequency circuit
- Highly stable design for critical needs

RoHS Compliant

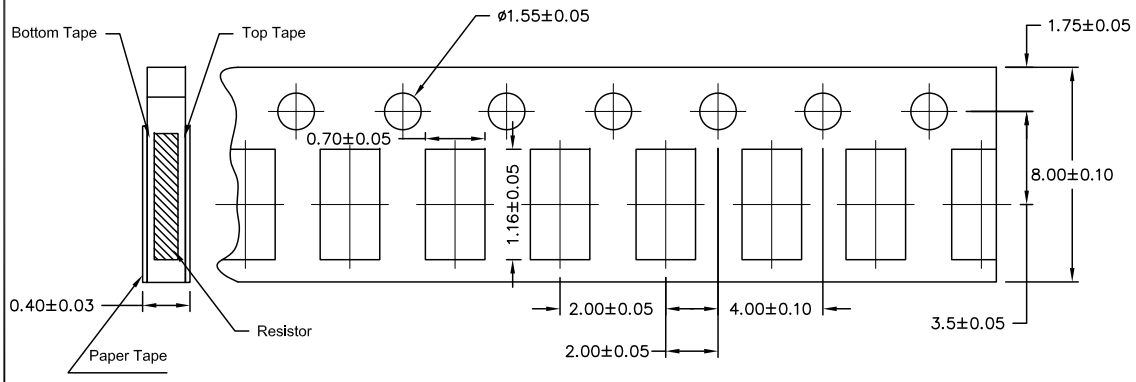


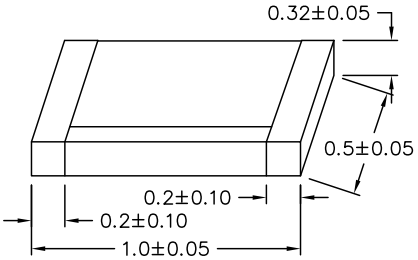


Application

-Cellular Phone, Pagers and GPS Products
-VCO, TCXO, Circuit an dRF Transceiver Module
-Wireless LAN Bluetooth module, Communication Appliances

Tape Dimension





DISCLAIMER:
ALL STATEMENTS AND TECHNICAL INFORMATION CONTAINED HEREIN ARE BASED UPON INFORMATION AND/OR TESTS WE BELIEVE TO BE ACCURATE AND RELIABLE. SINCE CONDITIONS OF USE ARE BEYOND OUR CONTROL, THE USER SHALL DETERMINE THE SUITABILITY OF THE PRODUCT FOR THE INTENDED USE AND ASSUME ALL RISK AND LIABILITY WHATSOEVER IN CONNECTION THEREWITH.

TOLERANCES:
UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE FOR REFERENCE PURPOSES ONLY.

DRAWN BY:	DATE:
Jason Nash	05/21/09
CHECKED BY:	DATE:
JWM	05/21/09
APPROVED BY:	DATE:
JWM	05/21/09

DRAWING TITLE: Thin Film Chip Inductor – Case size 0402

SIZE	DWG. NO.	ELECTRONIC FILE	REV
A	Ta-1127	Ta-1127.DWG	A

SCALE: NTS | U.O.M.: Millimeters | SHEET: 1 OF 2

Downloaded from Elcodis.com electronic components distributor

RoHS Compliant

	Item	Specification	Test Method
1	Bending Test	As SPEC.	JIS-C-5202-6.1.4 Bending Amplitude 3mm for 10 seconds
2	Dielectric Withstand Voltage	>100V	MIL-STD-202F Method 301. Apply 100VA (rms) for 1minute.
3	Insulation Resistance	>1000MΩ	MIL-STD-202F Method 302 Apply 100VDC for 1minute.
4	Resistance to Soldering Heat	△L<10%	MIL-STD-202F Method 210E 260±5°C, 10±1seconds
5	High Temperature Exposure	△L<10%	JIS-C-5202-7.2 85±2°C, 1000 +48/-0 hours
6	Moisture Resistance	△L<10%	MIL-STD-202F Method 103B 40±2°C, 90~95%RH, 1000 +48/-0 hours
7	Low Temperature Storage	△L<10%	JIS-C-5202-7.1 -40±3°C, 1000 +48/-0 hours
8	Temperature Cycle	△L<10%	JIS-C-5202-7.4 -40/RT/85/RT, 10 cycles
9	Solderability	95% min coverage	MIL-STD-202F Method 208H 245°C ±5°C,3±0.5(sec)

Mfr PN	Inductance	Inductance Tolerance	DC Resistance Max	DC Current Rating	Self Resonant Frequency	Package/ Case	Q Factor	Test Frequency
MCFT000000	1nH	±0.1 nH	0.15ohm	700mA	13GHz	402	Q Factor:13	500MHz
MCFT000001	1.5nH	±0.1 nH	0.25ohm	700mA	10GHz	402	Q Factor:13	500MHz
MCFT000002	2.2nH	±0.1 nH	0.35ohm	440mA	8GHz	402	Q Factor:13	500MHz
MCFT000003	3.3nH	±0.1 nH	0.45ohm	380mA	6GHz	402	Q Factor:13	500MHz
MCFT000004	4.7nH	±0.1 nH	0.65ohm	320mA	5GHz	402	Q Factor:13	500MHz
MCFT000005	6.8nH	±0.1 nH	1.05ohm	260mA	5GHz	402	Q Factor:13	500MHz
MCFT000006	8.2nH	±0.1 nH	1.25ohm	220mA	4GHz	402	Q Factor:13	500MHz
MCFT000007	10nH	±1%	1.35ohm	200mA	4GHz	402	Q Factor:13	500MHz
MCFT000008	15nH	±1%	1.75ohm	130mA	3GHz	402	Q Factor:13	500MHz
MCFT000009	22nH	±1%	2.65ohm	90mA	2GHz	402	Q Factor:13	500MHz
MCFT000010	33nH	±1%	4.5ohm	75mA	1.5GHz	402	Q Factor:13	500MHz

ALL RIGHTS RESERVED. NO PORTION OF THIS PUBLICATION, WHETHER IN WHOLE OR IN PART CAN BE REPRODUCED WITHOUT THE EXPRESS WRITTEN CONSENT OF SPC TECHNOLOGY.

SIZE	DWG. NO.	ELECTRONIC FILE	REV
A	Ta-1127	Ta-1127.DWG	A

Downloaded from Elcodis.com electronic components distributor